



### Complementary Enhancement Mode MOSFET - ESD Protected

Voltage

50 / -60V

Current

0.4A / -0.25A

#### **Features**

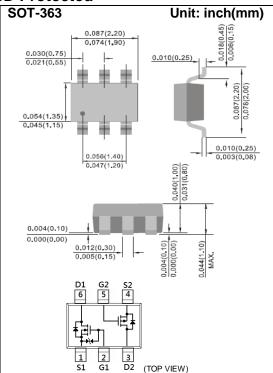
- Advanced Trench Process Technology
- Specially Designed for Switch Load, PWM Application, etc.
- ESD Protected 2KV HBM
- Lead free in compliance with EU RoHS 2011/65/EU directive
- Green molding compound as per IEC61249 Std. (Halogen Free)

### **Mechanical Data**

• Case: SOT-363 Package

• Terminals: Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.0002 ounces, 0.006 grams



## **Maximum Ratings and Thermal Characteristics** (T<sub>A</sub>=25 °C unless otherwise noted)

PARAMETE	SYMBOL	N-Ch LIMIT	P-Ch LIMIT	UNITS	
Drain-Source Voltage		V <sub>DS</sub>	50	-60	V
Gate-Source Voltage		V <sub>GS</sub>	<u>+</u> 20	<u>+</u> 20	V
Continuous Drain Current		I <sub>D</sub>	400	-250	mA
Pulsed Drain Current (Note 4)		I <sub>DM</sub>	1200	-900	mA
D D: : ::	T <sub>a</sub> =25°C		350		mW
Power Dissipation	Derate above 25°C	P <sub>D</sub>	2	mW/°C	
Operating Junction and Storage Temperature Range		$T_{J}$ , $T_{STG}$	-55~150		°C
Typical Thermal resistance					
- Junction to Ambient (Note 3)		$R_{\theta JA}$	3.5	°C/W	





## N-Channel Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}$ =0V, $I_D$ = 250uA	50	-	-	V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=250uA$	0.5	0.9	1.0	V	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_{D} = 500mA$	-	1.2	1.5	Ω	
		$V_{GS}$ = 4.5V, $I_{D}$ = 200mA	-	1.3	2.5		
Zero Gate Voltage Drain Current	$I_{DSS}$	V <sub>DS</sub> = 50V, V <sub>GS</sub> =0V	-	-	1	uA	
Gate-Source Leakage Current	$I_{GSS}$	V <sub>GS</sub> = <u>+</u> 20V, V <sub>DS</sub> =0V	-	-	<u>+</u> 10	uA	
Dynamic (Note 5)							
Total Gate Charge	$Q_g$	V <sub>DS</sub> =25V, I <sub>D</sub> =500mA, V <sub>GS</sub> =4.5V	-	0.95	-	nC	
Gate-Source Charge	$Q_gs$		-	0.34	-		
Gate-Drain Charge	$Q_gd$		-	0.32	-		
Input Capacitance	Ciss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHZ	-	36	-	pF	
Output Capacitance	Coss		-	11	-		
Reverse Transfer Capacitance	Crss		-	6.6	-		
Turn-On Delay Time	td <sub>(on)</sub>	\/ O5\/   500~ A	-	2.3	-		
Turn-On Rise Time	tr	$\begin{array}{c} V_{DD}\text{=}25\text{V, I}_{D}\text{=}500\text{mA,} \\ V_{GS}\text{=}10\text{V,} \\ R_{G}\text{=}6\Omega \end{array}$	-	20	-		
Turn-Off Delay Time	td <sub>(off)</sub>		-	7	-	ns	
Turn-Off Fall Time	tf		-	20	-		
Drain-Source Diode							
Maximum Continuous Drain-Source					400	mA	
Diode Forward Current	I <sub>S</sub>		-	-	400	IIIA	
Diode Forward Voltage	$V_{\mathtt{SD}}$	I <sub>S</sub> = 500mA, V <sub>GS</sub> =0V	-	0.9	1.5	V	

#### NOTES:

- 1. Pulse width<a></a>300us, Duty cycle<a></a>2%
- 2. Essentially independent of operating temperature typical characteristics.
- 3. ROJA is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper.
- 4. The maximum current rating is package limited.
- 5. Guaranteed by design, not subject to production testing.





# P-Channel Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V,I <sub>D</sub> =-250uA	-60	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=-250uA$	-1.0	-1.5	-2.5	V
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V,I <sub>D</sub> =-500mA	-	2.4	4	Ω
		V <sub>GS</sub> =-4.5V,I <sub>D</sub> =-200mA	-	2.7	6	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-48V,V <sub>GS</sub> =0V	-	-	-1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = <u>+</u> 20V,V <sub>DS</sub> =0V	ı	-	<u>+</u> 100	nA
Dynamic (Note 5)						
Total Gate Charge	$Q_g$	V <sub>DS</sub> =-25V, I <sub>D</sub> =-100mA, V <sub>GS</sub> =-4.5V	-	1.1	-	nC
Gate-Source Charge	$Q_gs$		-	0.3	-	
Gate-Drain Charge	$Q_gd$		-	0.2	-	
Input Capacitance	Ciss	V <sub>DS</sub> =-25V, V <sub>GS</sub> =0V, f=1.0MHZ	-	51	-	pF
Output Capacitance	Coss		-	15	-	
Reverse Transfer Capacitance	Crss		ı	2.2	-	
Turn-On Delay Time	td <sub>(on)</sub>	$V_{DD}$ =-25V, $I_{D}$ =-100mA, $V_{GS}$ =-10V, $R_{G}$ =6 $\Omega$ (Note 1,2)	ı	4.8	-	
Turn-On Rise Time	tr		ı	19	-	
Turn-Off Delay Time	td <sub>(off)</sub>		-	52	-	ns
Turn-Off Fall Time	tf		ı	32	-	
Drain-Source Diode						
Maximum Continuous Drain-Source	I <sub>S</sub>				250	
Diode Forward Current			-	-	-250	mA
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> =-500mA, V <sub>GS</sub> =0V	-	-0.9	-1.5	V





#### **N-Channel TYPICAL CHARACTERISTIC CURVES**

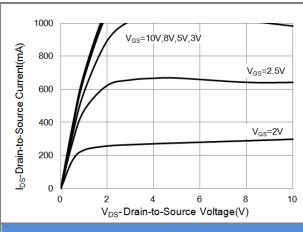


Fig.1 On-Region Characteristics

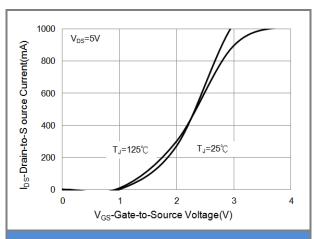


Fig.2 Transfer Characteristics

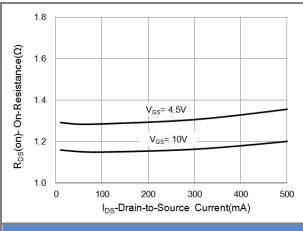


Fig.3 On-Resistance vs. Drain Current

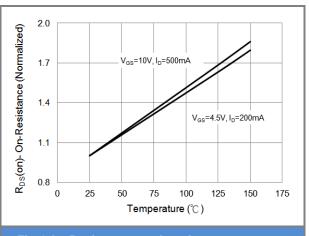
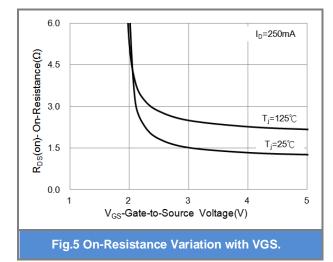
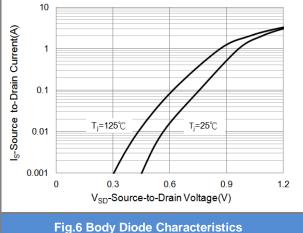


Fig.4 On-Resistance vs. Junction temperature

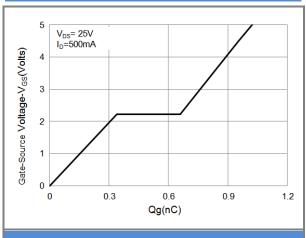








### **N-Channel TYPICAL CHARACTERISTIC CURVES**



**Fig.7 Gate-Charge Characteristics** 

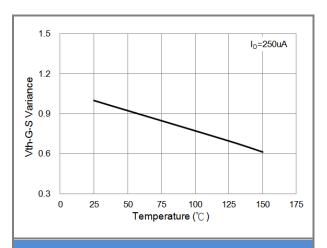


Fig.8 Threshold Voltage Variation with Temperature.

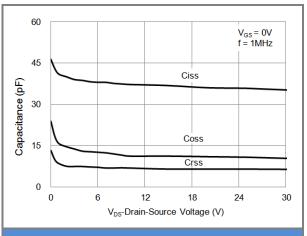


Fig.9 Capacitance vs. Drain-Source Voltage.





#### P-Channel TYPICAL CHARACTERISTIC CURVES

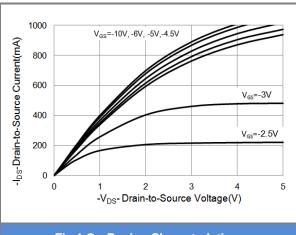
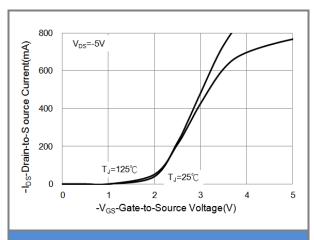


Fig.1 On-Region Characteristics



**Fig.2 Transfer Characteristics** 

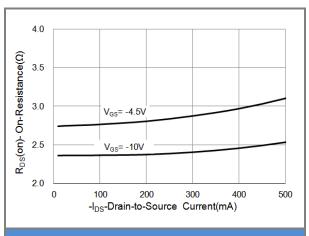


Fig.3 On-Resistance vs. Drain Current

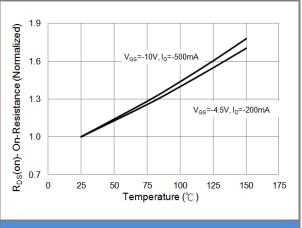
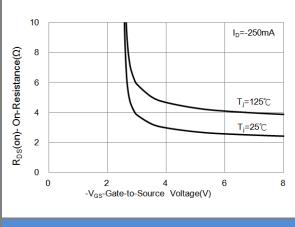
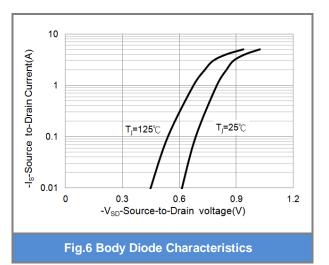


Fig.4 On-Resistance vs. Junction temperature











### P-Channel TYPICAL CHARACTERISTIC CURVES

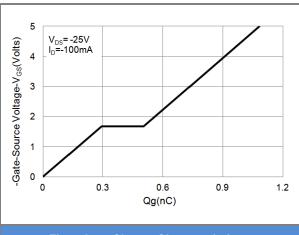


Fig.7 Gate-Charge Characteristics

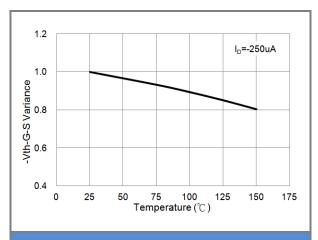


Fig.8 Threshold Voltage Variation with Temperature.

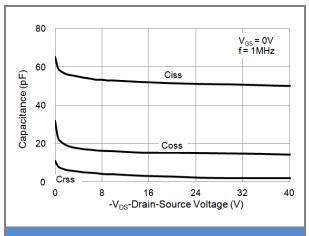


Fig.9 Threshold Voltage Variation with Temperature.

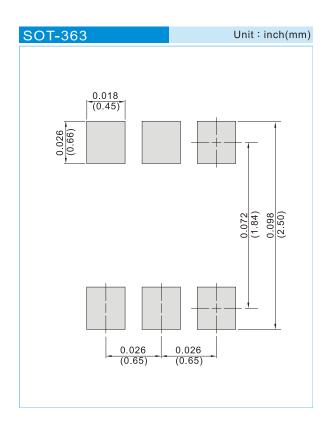




### PART NO PACKING CODE VERSION

Part No Packing Code	Package Type	Packing type	Marking	Version
PJT7603_R1_00001	SOT-363	3K pcs / 7" reel	T63	Halogen free
PJT7603_R2_00001	SOT-363	10K pcs / 13" reel	T63	Halogen free

### **MOUNTING PAD LAYOUT**







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